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MB2146-220

F^{2}MC-8FX Family LQFP-64P (0.5mm Pitch) Header Board Operation Guide

Doc. # 002-07326 Rev. *A

Cypress Semiconductor
198 Champion Court
San Jose, CA 95134-1709
Phone (USA): 800.858.1810
Phone (Intnl): +1.408.943.2600
www.cypress.com

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Preface

Thank you for purchasing the LQFP-64P (0.5 mm pitch) *1 header board (MB2146-220) for the F2MC *2 -8FX family.

The LQFP-64P header board is used in the header board unit to connect the MCU board (MB2146-3xx) which mounted F2MC-8FX family evaluation MCU board to a user system.

This manual explains the handling of the MB2146-220 header board for the F2MC-8FX family. Before using the MB2146-220 header board, be sure to read this manual.

Consult the Sales representatives or the Support representatives of Cypress for mass-produced MCUs and evaluation MCUs which correspond on a MB2146-220 header board.

*1: The lead pitch of PACKAGE (FPT-64P-M03) is 0.5 mm and the body size is 10 mm × 10 mm.
*2: mm.Using the product safely.

■ Caution of the products described in this document

The following precautions apply to the product described in this manual.

CAUTION	The wrong use of a device will give an injury and may cause malfunction on customers system.

Cuts	This product has parts with sharp points that are exposed. Do not touch edge of the product with your bare hands.
Damage	When connect the header board to the user system, correctly position the index mark (▲) on the NQPACK mounted on the user system with the 1 pin direction(1) on the header board, otherwise the MCU bord and user system might be damaged.
Damage	When mounting a mass production MCU, correctly position pin 1, otherwise the mass production MCU and user system might be damaged.

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1. Product outline

1.1 Product outline

This product is a header board used to connect the MCU board (Part number : MB2146-3xx) carrying an evaluation MCU in the F^{2}MC-8FX Family of Cypress 8-bit microcontrollers to a user system. To build an F^{2}MC-8FX evaluation environment, combine three products: the header board, MCU board, and BGM adapter (Part number : MB2146-09).

For more information please visit our following websites:

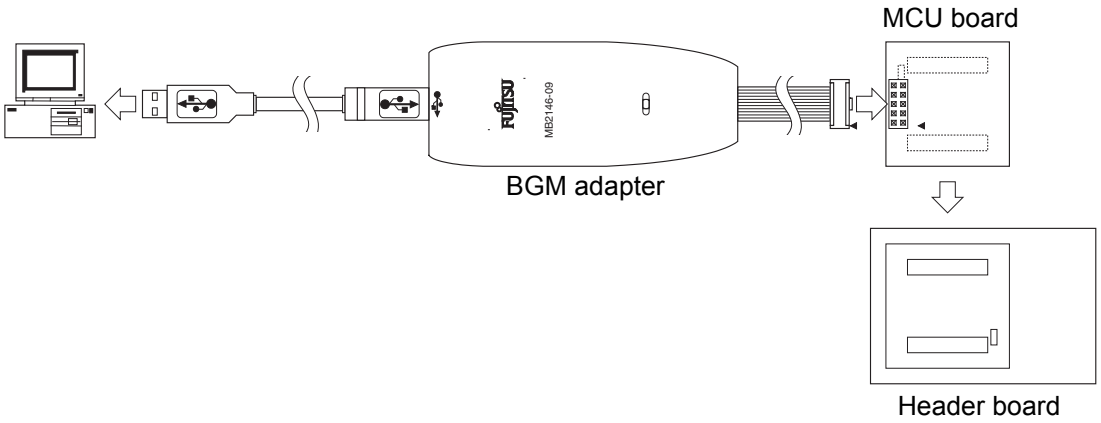
http://www.cypress.com/documentation/development-kitsboards/mb2146-220

http://www.cypress.com/documentation/development-kitsboards/mb2146-09a-e

http://www.cypress.com/documentation/development-kitsboards/mb2146-301a-e

http://www.cypress.com/documentation/development-kitsboards/mb2146-303a-e

Figure 1-1. System-configuration



1.2 Product configuration

Tables 1-1, and Table 1-2. list the product configuration in the header board package and options.

Table 1-1. Product Cofiguration

Name	Description	Remarks
F^2MC-8FX LQFP-64P (0.5 mm pitch) Header board [Part number:MB2146-220]	Connector/LQFP64pin (0.5 mm pitch) Package conversion	—
[Part number : YQPACK064SD] (Tokyo Eletech Corporation)	Header board-I/F between NQPACK	Include (Finishing connection)
[Part number : NQPACK064SD] (Tokyo Eletech Corporation)	User system mounting	Include
[Part number : HQPACK064SD] (Tokyo Eletech Corporation)	It is used at the time of mass-production MCU mounting to NQPACK.	Include

Table 1-2. Option (sold separately)

Name	Description	Remarks
BGM adapter [Part number : MB2146-09]	The ICE unit for F^2MC-8FX	—
MCU board [Part number : MB2146-3xx]	MB95FV100-xxx Built in	F^2MC-8FX evaluation MCU Built in *

* : Several types of evaluation MCUs are available depending on their applications. Purchase the one that satisfy the service conditions.

2. Checking the Delivered Product

Before using the LQFP-64P header board, confirm that the following components are included in the box:

- LQFP-64P (0.5 mm pitch) Header board *1 : 1
- Screws for securing Header board (M2 × 10 mm, 0.4 mm pitch) : 4
- NQPACK064SD *2 : 1
- HQPACK064SD *3 : 1
- Operation manual (English version, this manual) : 1

*1: Referred to as “header board”. Header board is mounted on YQPACK064SD (Tokyo Eletech Corporation), referred to as “YQPACK”.
*2: IC socket manufactured by Tokyo Eletech Corporation, referred to as “NQPACK”, and supplied with a special screwdriver and 2 guide pins. A socket offering higher reliability, NQPACK064SD-SL (Tokyo Eletech Corporation, sold separately), can be used by making an IC socket mounting hole on the user system board.For more information,contact Tokyo Eletech Corporation.
*3: IC socket cover manufactured by Tokyo Eletech Corporation,referred to as “HQPACK”, with 4 screws for securing HQPACK(M2 × 6 mm, 0.4 mm pitch).

3. Handling Precautions

The header board is precision-manufactured to improve dimensional accuracy and to ensure reliable contact. The header is therefore sensitive to mechanical shock. To ensure correct use of the header in the proper environment, observe the following points regarding its insertion and removal:

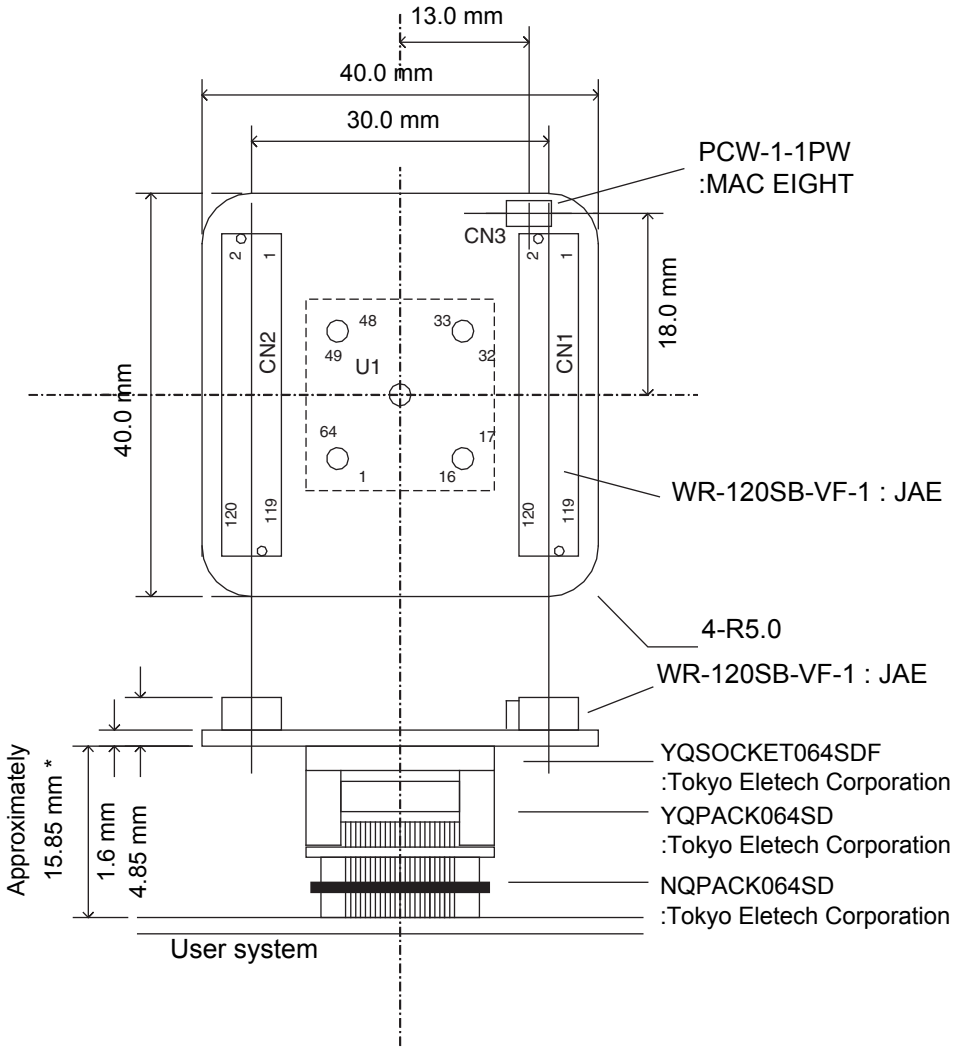
- To avoid placing stress on the NQPACK mounted on the user system board during connecting the header board.

4. Notes on Designing

4.1 Restrictions of PC board for the user system

If a tall component is mounted around the NQPACK mounted on the user system, the header board connected to the user system touches the component. To prevent this, design the pc board of the user system such that the height specified in Figure 4-1 is not exceeded. Figure 4-1 shows dimension figure of the header board.

Figure 4-1. Header board dimensions



U1:User system I/F connector

CN3:Incorrect insertion preventive socket

CN1/CN2:MCU board I/F connector

* : The height differs slightly depending on how the socket are engaged.

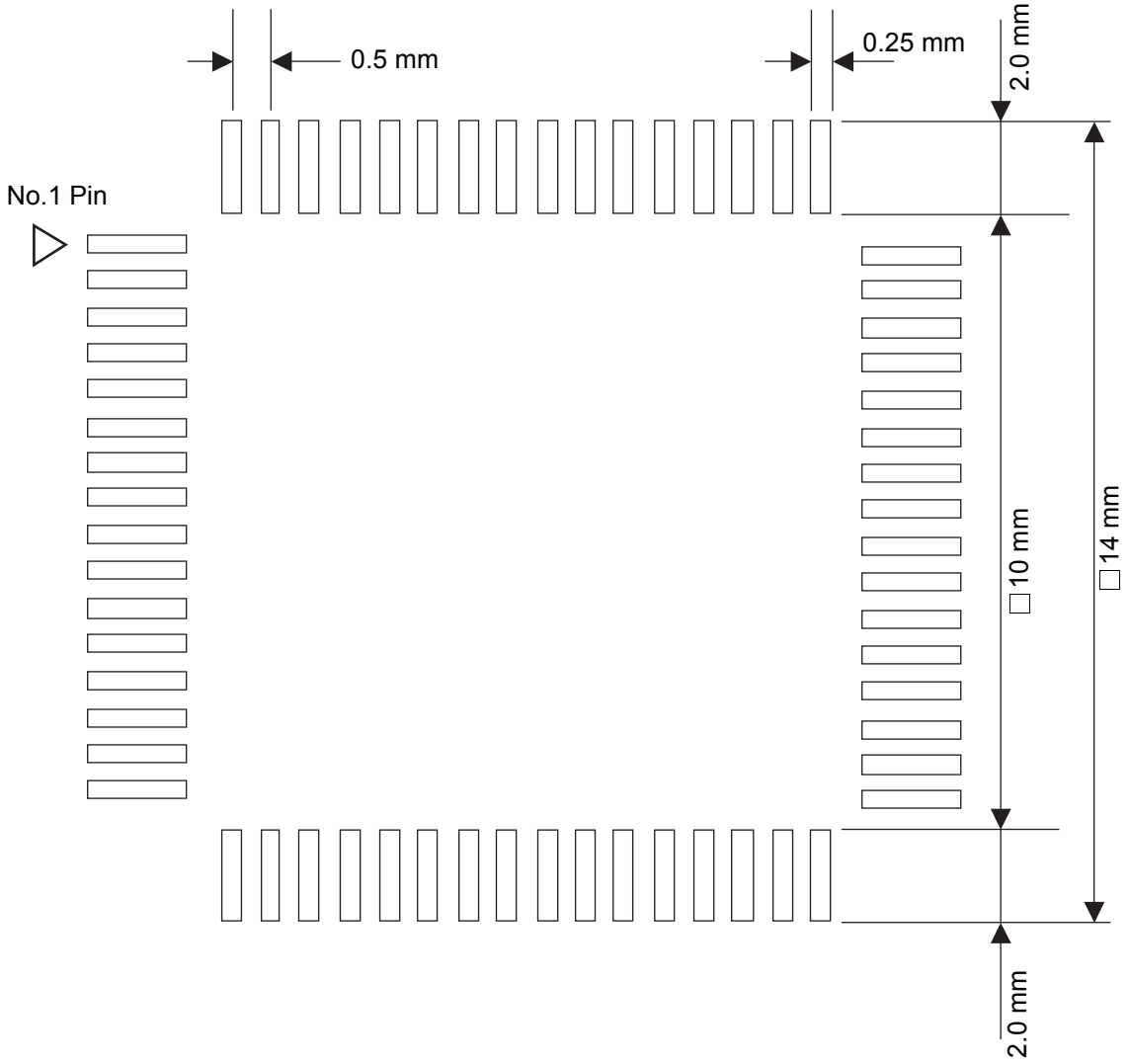
4.2 MCU footprint design notes

Figure 4-2 shows the recommended dimensions of the NQPACK footprint mounted on the PC board of the user system.

The PC board of the user system must be designed with due consideration given to this footprint as well as to the mass production MCU.

To follow updated information, be sure to contact Tokyo Eletech Corporation whenever designing the PC board.

Figure 4-2. Recommended dimensions of the footprint for mounting the NQPACK



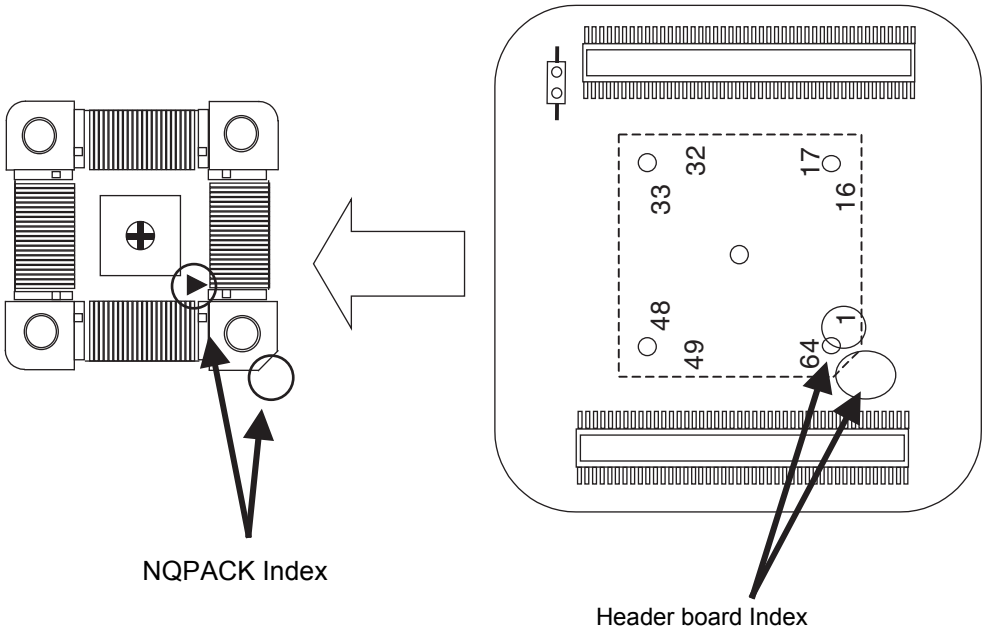
5. Procedure for Connecting the User System

5.1 Connecting

Before using the LQFP-64P (0.5 mm pitch) header board, mount the supplied NQPACK on the user system.

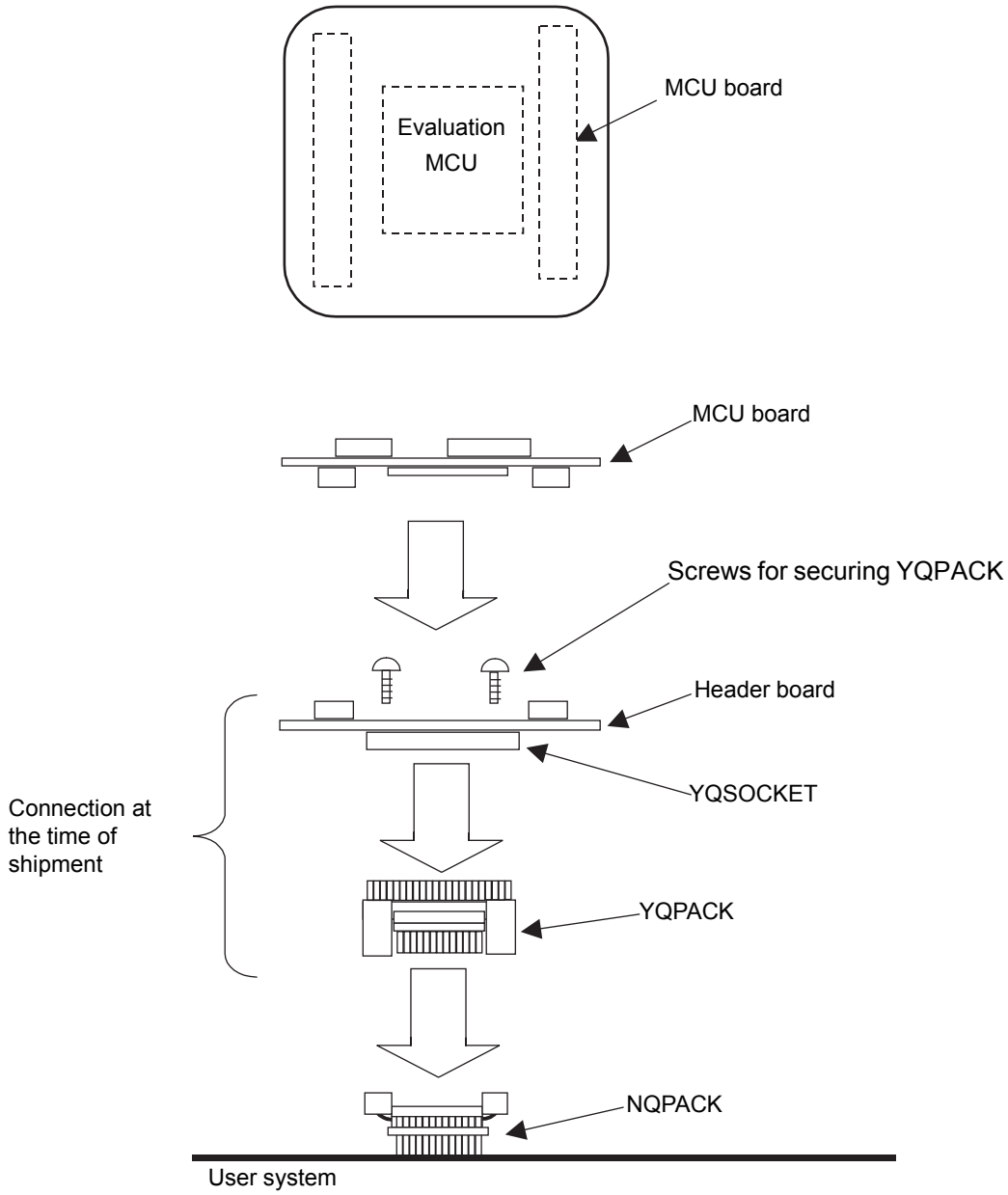
1. To connect the header board to the user system, match the index mark (▲) on the NQPACK mounted on the user system with the index mark (the notched corner of silk-screen printing) on the header board and then insert it (See Figure 5-1) . The pin of YQPACK is thin and easy to bent. Insert NQPACK after confirm that the pin of YQPACK is not bent.

Figure 5-1. Index Position



2. Insert each screw for securing header board in each of the four drilled holes on the header board, and then first tighten the screws in opposing corners followed by the two remaining screws (See Figure 5-1) . The center screw hole is not used.
   To tighten the screws, use the special screwdriver supplied with the NQPACK to finally tighten the four screws in sequence. Tightening the screws too tight might result in a defective contact.
3. Connect the MCU board to the header board while being careful not to excessively force the NQPACK. The MCU board can be connected to the header board only in the correct orientation as they have a Incorrect insertion header socket to prevent reverse connection. Figure 5-2 illustrates how the MCU board, header board, NQPACK, and user system are connected together.

Figure 5-2. MCU board / header board Connection



5.2 Disconnection

1. Remove the MCU board from the header board. Detach the four corners slowly in sequence not to excessively force the junction with the NQPACK.
2. Remove all of the four screws from the header board.
3. Pull out the header board vertically from the NQPACK. Remove the header board slowly not to excessively force the junction with the NQPACK.

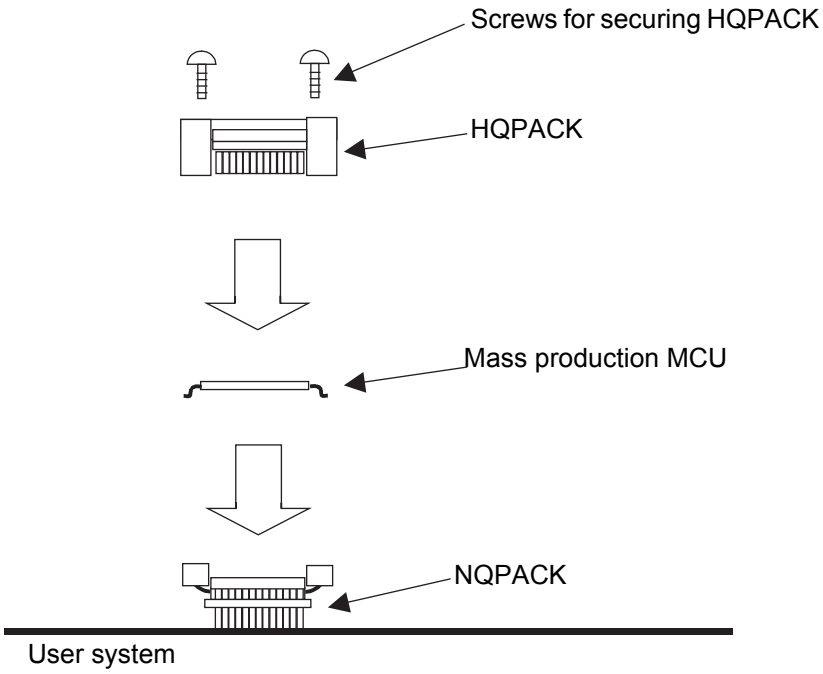
6. Mounting Mass Production MCUs

To mount a mass production MCU on the user system, use the supplied HQPACK (See Figure 6-1).

6.1 Mounting

1. To mount a mass production MCU on the user system, match the index mark (▲) on the NQPACK mounted on the user system with the index mark (●) on the mass production MCU.
2. Confirm that the mass production MCU is correctly mounted on the NQPACK. Next, insert the HQPACK into a NQPACK.
   The pin of HQPACK is thin and easy to bent. Insert NQPACK after confirm that the pin of HQPACK is not bent.
3. Insert each screw for securing HQPACK in each of four drilled holes on the HQPACK, and then first tighten the screws in opposing corners followed by the two remaining screws.
   To tighten the screws, use the special screwdriver supplied with the NQPACK to finally tighten the four screws in sequence. Tightening the screws too tight might result in a defective contact.

Figure 6-1. Mounting a mass production MCU



6.2 Disconnection

To remove the HQPACK, remove all of the four screws and pull out the HQPACK vertically from the NQPACK. If you take out an Mass production MCU, use a dropper jig dedicated to IC removal to remove the Mass production MCU by suction force. Do not attempt to remove the Mass production MCU forcibly, for example, using a screwdriver as doing so can bend the Mass production MCU leads or break the NQPACK.

7. Product specification

7.1 General specification

The general specification of a header board is shown in Table 7-1.

Table 7-1. General Specification

Item	Description
Operating/storage temperature	5°C to 35°C (At the time of operation) 0°C to 40°C (At the time of storage)
Operating/storage humidity	20% to 80% (At the time of operation) 20% to 80% (At the time of storage)
Dimensions	40 mm × 40 mm × 16 mm (Height contains YQPACK and NQPACK)
Weight	Header board : About 11g

7.2 Main Composition

The main composition component of a header board is shown in Table 7-2.

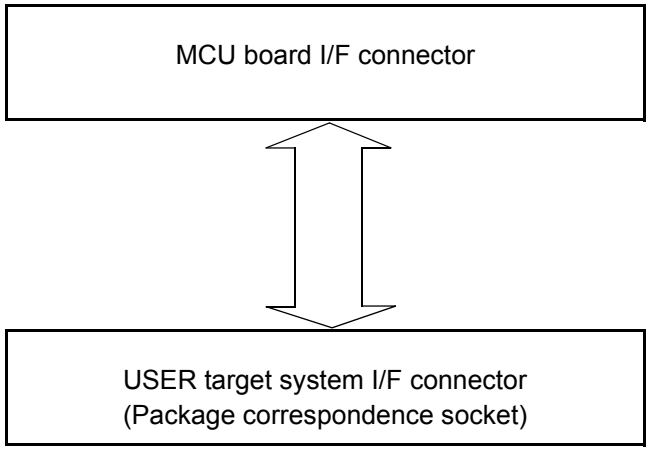
Table 7-2. Main Composition

Item	Description
MCU board I/F connector	120 pins 0.5 mm pitch 2 piece connector (straight) × 2 [Model number: WR-120SB-VF-1 (JAE)]
Incorrect insertion preventive socket	2 pins 2.54 mm pitch 1 piece socket (Straight) [Model number:PCW-3-1-1PW (MAC EIGHT)]
User target system I/F connector	socket 64 pin 0.5 mm pitch [Model number:YQSOCKET064SDF (Tokyo Eletech Corporation)]

7.3 Functional block diagram

A header board performs socket conversion between the I/F connector of a MCU board, and YQPACK. Parts, such as IC, are not in an inside. A block diagram is shown in Figure 7-1.

Figure 7-1. Functional block diagram



7.4 MCU board I/F connector(CN1/CN2/CN3)

CN1 and CN2 are MCU board I/F connectors. CN3 is the incorrect insertion prevention socket of a MCU board. The pin assignment of the MCU board I/F connector CN1 is shown in Table 7-2, and the pin assignment of the MCU board I/F connector CN2 is shown in Table 7-3.

Table 7-3. Pin assignment of the MCU board I/F connector CN1

Connect or Pin Numbers	Evaluation MCU Pin Numbers	Signal name	Connect or Pin Numbers	Evaluation MCU Pin Numbers	Signal name	Connect or Pin Numbers .	Evaluation MCU Pin Numbers	Signal name
1	A9	PC4	41	E2	LVR3	81	P3	BSOUT
2	B9	PC1	42	E1	LVSS	82	P4	BDBMX
3	C9	PC2	43	F4	LVDREXT	83	R1	P83
4	D9	PC3	44	F3	LVDBGR	84	R2	BRSTX
5	A8	PC0	45	F2	LVDENX	85	R3	X0A
6	B8	PB4	46	F1	P22A	86	R4	RSTX
7	C8	PB5	47	–	GND	87	T1	ROMS1
8	D8	PB6	48	–	GND	88	T2	BSIN
9	A7	PB7	49	G4	P20A	89	T3	Vss
10	B7	PB2	50	G3	NC1	90	T4	X0
11	C7	PB0	51	G2	P21A	91	U1	BEXCK
12	D7	PB1	52	G1	P23A	92	U2	X1
13	A6	PB3	53	H4	P24A	93	U3	MOD
14	B6	PA2	54	H3	P25A	94	U4	PF2
15	C6	P95	55	H2	P26A	95	V1	X1A
16	D6	PA0	56	H1	P27A	96	V2	Vcc53
17	A5	PA3	57	J4	P24B	97	–	GND
18	B5	P94	58	J3	P50	98	–	GND
19	C5	P90	59	J2	P23B	99	V3	PINT0
20	D5	P91	60	J1	P51	100	V4	PSEL_EXT
21	A4	PA1	61	K1	P52	101	R5	PF1
22	A3	P93	62	K2	P55	102	T5	PF0
23	–	GND	63	K3	P54	103	U5	NC2
24	–	GND	64	K4	P53	104	V5	PENABLE
25	A2	CSVENX	65	L1	P70	105	R6	APBENX
26	A1	Vss	66	L2	P74	106	T6	PINT1
27	B4	P92	67	L3	P73	107	U6	PCLK
28	B3	TCLK	68	L4	P72	108	V6	PADDR0
29	B2	LVCC	69	M1	P71	109	R7	PACTIVE
30	B1	LVDIN	70	M2	P76	110	T7	PLOCK
31	C4	Cpin	71	M3	P80	111	U7	PWRITE
32	C3	Vcc51	72	M4	P77	112	V7	PADDR1
33	C2	LVDENX2	73	–	GND	113	R8	PADDR2
34	C1	LVR4	74	–	GND	114	T8	PADDR3
35	D4	TESTO	75	N1	P75	115	U8	PADDR4
36	D3	LVDOUT	76	N2	P82	116	V8	PADDR5
37	D2	LVR2	77	N3	PG0	117	R9	PADDR7
38	D1	BGOENX	78	N4	P84	118	T9	PRDATA0
39	E4	LVR1	79	P1	P81	119	U9	PADDR6
40	E3	LVR0	80	P2	ROMS0	120	V9	PRDATA1

Table 7-4. Pin assignment of the MCU board I/F connector CN2

Connector Pin Numbers	Evaluation MCU Pin Numbers	Signal name	Connector Pin Numbers	Evaluation MCU Pin Numbers	Signal name	Connector Pin Numbers	Evaluation MCU Pin Numbers	Signal name
1	A10	PC5	41	E17	NC4	81	P16	P34
2	B10	PD0	42	E18	SEL0	82	P15	P35
3	C10	PC6	43	F15	SEL3	83	R18	P44
4	D10	PC7	44	F16	SEL4	84	R17	P36
5	A11	PD1	45	F17	SEL1	85	R16	P31
6	B11	PD2	46	F18	P04C	86	R15	AVcc3
7	C11	PD3	47	–	GND	87	T18	P40
8	D11	PD4	48	–	GND	88	T17	P32
9	A12	PD5	49	G15	P06C	89	T16	AVss
10	B12	PD7	50	G16	P07C	90	T15	AVR
11	C12	P61	51	G17	P05C	91	U18	P33
12	D12	P60	52	G18	P00C	92	U17	P30
13	A13	PD6	53	H15	P01C	93	U16	AVR3
14	B13	P64	54	H16	P02C	94	U15	P15
15	C13	P66	55	H17	P03C	95	V18	AVcc
16	D13	P65	56	H18	P07A	96	V17	DA0
17	A14	P62	57	J15	P04A	97	–	GND
18	B14	PE0A	58	J16	P05A	98	–	GND
19	C14	PE3A	59	J17	P06A	99	V16	P14
20	D14	PE2A	60	J18	P03A	100	V15	P10
21	A15	P63	61	K18	P02A	101	R14	P16
22	A16	P67	62	K17	P07B	102	T14	DA1
23	–	GND	63	K16	P01A	103	U14	P13
24	–	GND	64	K15	P00A	104	V14	PWDATA7
25	A17	PE4A	65	L18	P06B	105	R13	P11
26	A18	Vcc54	66	L17	P05B	106	T13	P12
27	B15	PE1A	67	L16	P04B	107	U13	NC3
28	B16	PE5A	68	L15	P03B	108	V13	PWDATA3
29	B17	PE7A	69	M18	P02B	109	R12	PWDATA5
30	B18	PE3B	70	M17	P00B	110	T12	PWDATA6
31	C15	PE6A	71	M16	P46	111	U12	PWDATA4
32	C16	Vss	72	M15	P47	112	V12	PRDATA7
33	C17	PE2B	73	–	GND	113	R11	PWDATA0
34	C18	PE7B	74	–	GND	114	T11	PWDATA1
35	D15	PE1B	75	N18	P01B	115	U11	PWDATA2
36	D16	PE0B	76	N17	P43	116	V11	PRDATA6
37	D17	PE6B	77	N16	P41	117	R10	PRDATA3
38	D18	SEL2	78	N15	P42	118	T10	PRDATA4
39	E15	PE5B	79	P18	P45	119	U10	PRDATA5
40	E16	PE4B	80	P17	P37	120	V10	PRDATA2

7.5 User system I/F YQPACK (U1)

The user system I/F YQPACK pin assignment of a header board is shown in Table 7-5.

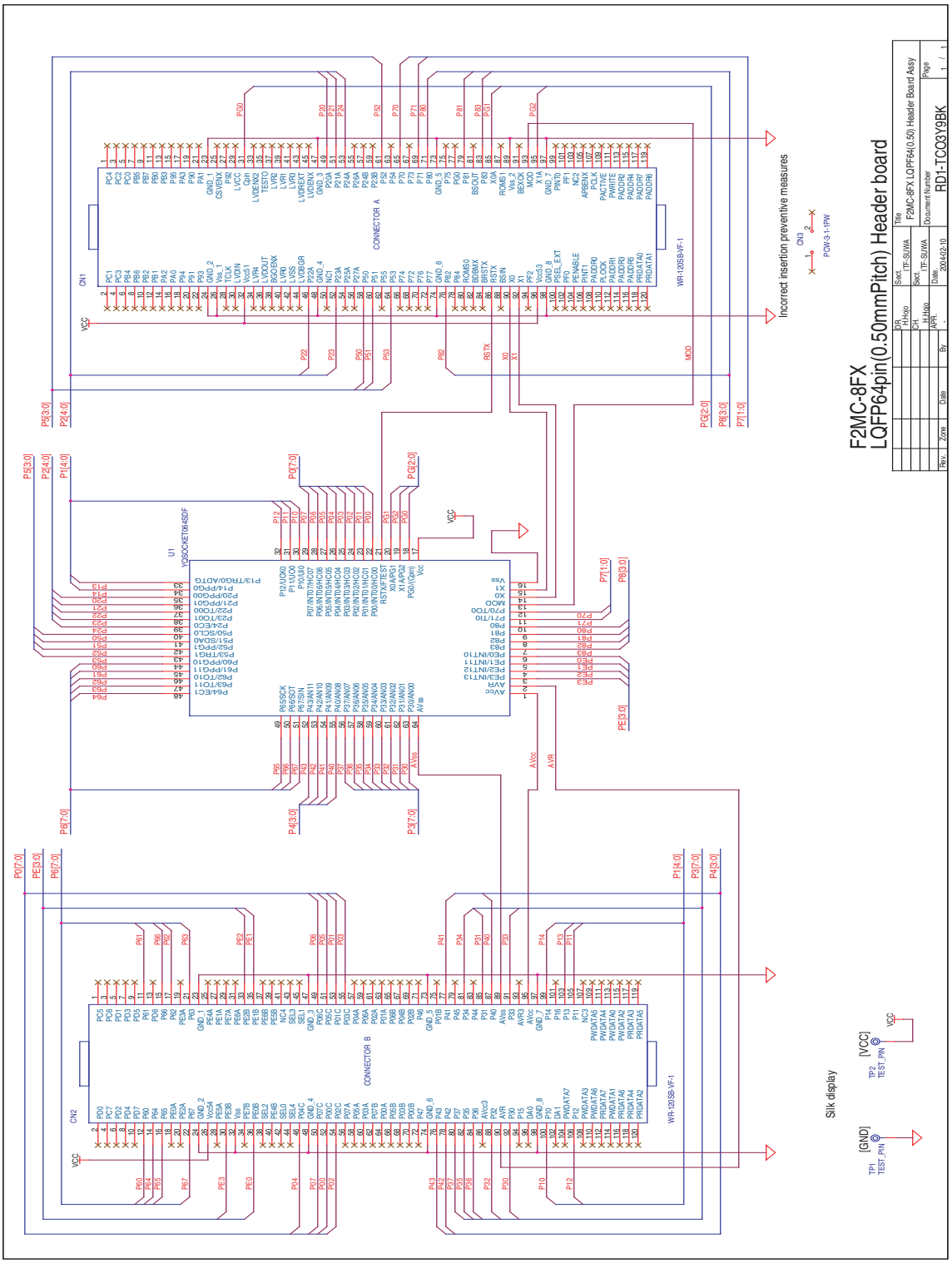
Table 7-5. Pin assignment of the User system I/F YQPACK

Connector Pin Numbers	Signal name	Connector Pin Numbers	Signal name
1	AVcc	33	P13/TRG0/ADTG
2	AVR	34	P14/PPG0
3	PE3/INT13	35	P20/PPG00
4	PE2/INT12	36	P21/PPG01
5	PE1/INT11	37	P22/TO00
6	PE0/INT10	38	P23/TO01
7	P83	39	P24/EC0
8	P82	40	P50/SCL0
9	P81	41	P51/SDA0
10	P80	42	P52/PPG1
11	P71/TI0	43	P53/TRG1
12	P70/TO0	44	P60/PPG10
13	MOD	45	P61/PPG11
14	X0	46	P62/TO10
15	X1	47	P63/TO11
16	VSS	48	P64/EC1
17	VCC	49	P65/SCK
18	PG0/(Cpin)	50	P66/SOT
19	X1A/PG2	51	P67/SIN
20	X0A/PG1	52	P43/AN11
21	RSTX/FTEST	53	P42/AN10
22	P00/INT00/HC00	54	P41/AN09
23	P01/INT01/HC01	55	P40/AN08
24	P02/INT02/HC02	56	P37/AN07
25	P03/INT03/HC03	57	P36/AN06
26	P04/INT04/HC04	58	P35/AN05
27	P05/INT05/HC05	59	P34/AN04
28	P06/INT06/HC06	60	P33/AN03
29	P07/INT07/HC07	61	P32/AN02
30	P10/UI0	62	P31/AN01
31	P11/UO0	63	P30/AN00
32	P12/UCK0	64	AVss

7.6 Circuit Diagram

The circuit diagram of a header board is shown in Figure 7-3.

Figure 7-2. Header board circuit diagram



Revision History

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**	–	09/13/2004	HUAL	Initial release
*A	5274552	05/26/2016	HUAL	Migrated Spansion Guide from SS01-26002-1E to Cypress format